

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS76815QD"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS76815QD	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D 8	3.91x4.9x1.58	85.2

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.001339	13	0.000001	0
Precious Metals	Gold	7440-57-5	0.074683	99.997322	999973	0.087609	876
Precious Metals	Silver	7440-22-4	0.000001	0.001339	13	0.000001	0
Sub-Total			0.074685	100	1000000	0.087612	876
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.665911	79.999976	800000	0.781168	7812
Thermoplastics	Epoxy	85954-11-6	0.166478	20.000024	200000	0.195292	1953
Sub-Total			0.832389	100	1000000	0.97646	9765
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	24.25509	97.41	974100	28.453194	284532
Copper and Its Alloys	Iron	7439-89-6	0.5976	2.4	24000	0.701033	7010
Copper and Its Alloys	Phosphorus	7723-14-0	0.00747	0.03	300	0.008763	88
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00747	0.03	300	0.008763	88
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00747	0.03	300	0.008763	88
Zinc and Its Alloys	Zinc	7440-66-6	0.0249	0.1	1000	0.02921	292
Sub-Total			24.9	100	1000000	29.209726	292097
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.355273	95.119946	951199	0.416764	4168
Precious Metals	Gold	7440-57-5	0.002913	0.77992	7799	0.003417	34
Precious Metals	Palladium	7440-05-3	0.015314	4.100134	41001	0.017965	180
Sub-Total			0.3735	100	1000000	0.438146	4381
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	49.582523	88	880000	58.164334	581643
Other Plastics and Rubber	Carbon Black	1333-86-4	0.169031	0.299999	3000	0.198287	1983
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.309891	0.55	5500	0.363527	3635
Thermoplastics	Epoxy	85954-11-6	6.282331	11.15	111500	7.369685	73697
Sub-Total			56.343776	100	1000000	66.095834	660958
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.721228	100	1000000	3.192222	31922
Sub-Total			2.721228	100	1000000	3.192222	31922
Total			85.245578			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, see Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.